ZYMET

Reworkable Underfill Enhances Board Level Thermal Cycling of IC Packages, Zymet CN-1735

July 17, 2013

EAST HANOVER, NJ – Zymet has introduced a new reworkable low-CTE underfill encapsulant, **CN-1735**, designed to enhance the board level thermal cycle performance of IC packages with pitches as fine as 0.3-mm pitch. **CN-1735** will also enhance ruggedness, for drop and bend test performance.

Conventional reworkable underfills have CTE's of 64-75 ppm/°C and are used primarily to enhance drop test and bend test performance, even if board level thermal cycle performance is sacrificed. **CN-1735** has a CTE of 40 ppm/°C to enhance thermal cycle performance.

Low CTE underfills are typically non-reworkable or very difficult to rework. **CN-1735** is easily reworked. Rework is accomplished by use of elevated temperature, 170°C to 180°C, to remove the underfill fillet. Then, the BGA is lifted from the board after heating it to reflow temperature. Underfill residue is easily scraped off, again at 170°C to 180°C.

Zymet is a manufacturer of microelectronic and electronic adhesives and encapsulants. Its products include die attach adhesives, substrate adhesives, UV curable glob top and cavity-fill encapsulants, and underfill encapsulants.

For more information, contact Zymet, Inc., East Hanover, NJ. Requests for information may also be submitted by Email to info@zymet.com

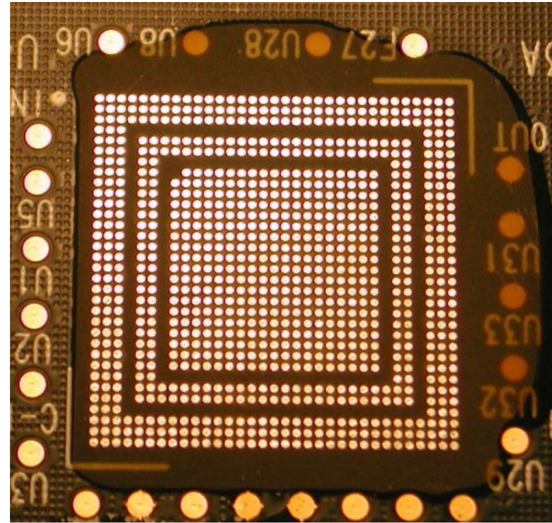

Figure 1. POP Underfilled with Reworkable Underfill.

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